2.0x1.25mm SMD CHIP LED LAMP

Part Number: APHCM2012ZGC/E-F01 Green



ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES

Features

- 2.0X1.25mm SMT LED,0.5mm max. thickness.
- Low power consumption.
- Wide viewing angle.
- Ideal for backlight and indicator.
- Various colors and lens types available.
- Package : 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

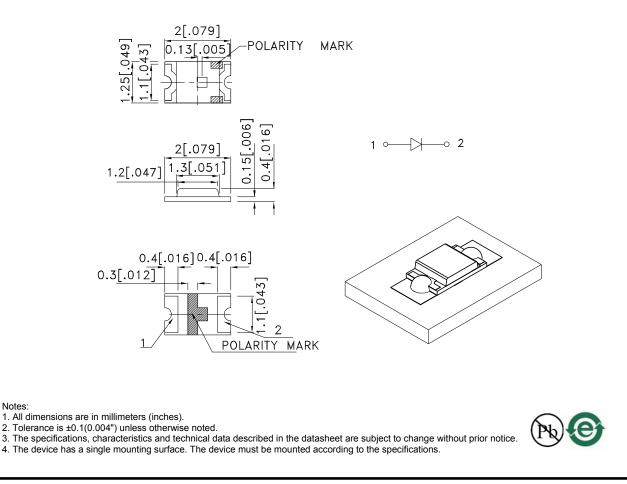
The Green source color devices are made with InGaN Light Emitting Diode.

Static electricity and surge damage the LEDS.

It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.

Package Dimensions



SPEC NO: DSAK0122 APPROVED: WYNEC REV NO: V.2 CHECKED: Allen Liu DATE: DEC/31/2009 DRAWN: Q.Q.Zhu PAGE: 1 OF 5 ERP: 1203010135

Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
APHCM2012ZGC/E-F01	Green (InGaN)	WATER CLEAR	280	650	110°

Notes:

1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

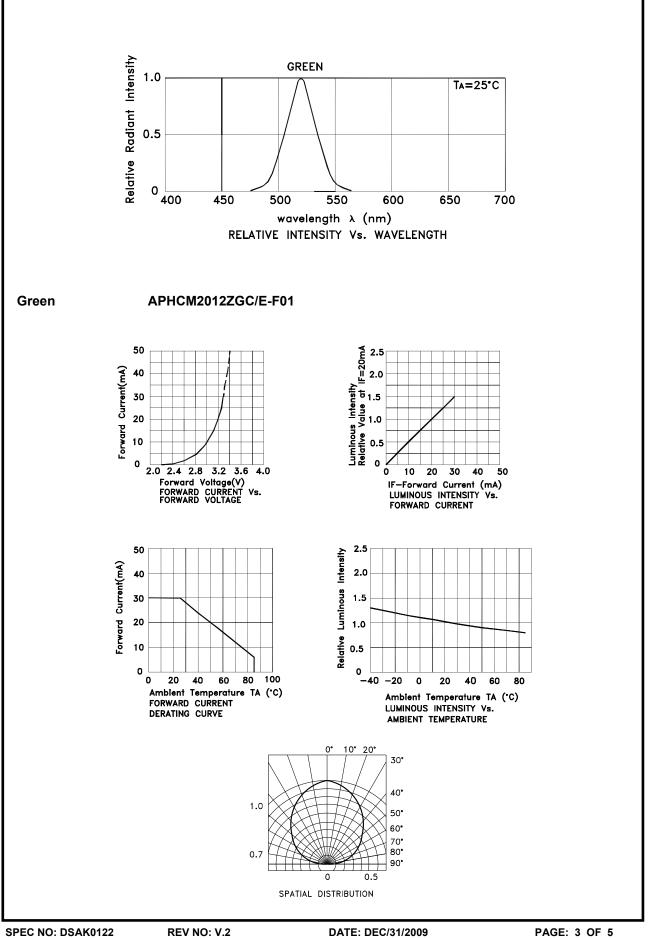
Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Green	520		nm	IF=20mA
λD [1]	Dominant Wavelength	Green	525		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	Green	35		nm	IF=20mA
С	Capacitance	Green	100		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Green	3.2	4	V	IF=20mA
lr	Reverse Current	Green		10	uA	VR=5V

Notes: 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

Parameter	Green	Units	
Power dissipation	120	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	100	mA	
Reverse Voltage	5	V	
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		

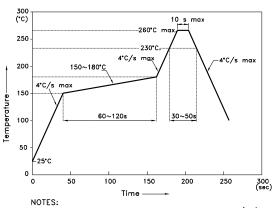
Note: 1. 1/10 Duty Cycle, 0.1ms Pulse Width.



APHCM2012ZGC/E-F01

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

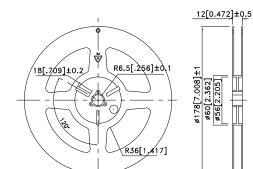
Reflow Soldering Profile For Lead-free SMT Process.



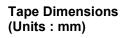
NOTES: 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature. 3.Number of reflow process shall be 2 times or less.

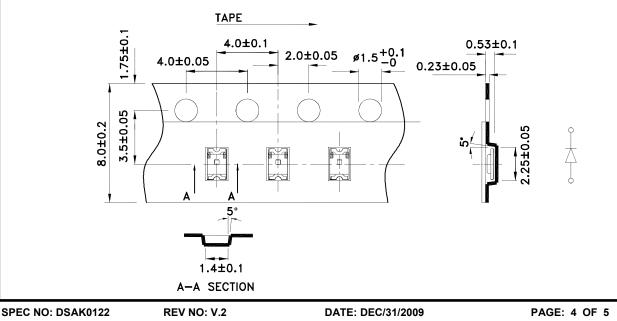


1.2 1.2 2 2.1 2.1



Reel Dimension





CHECKED: Allen Liu

DRAWN: Q.Q.Zhu

ERP: 1203010135

9[0.354]±0.2

